



# Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model  
[List multiple models if applicable.]

HP A7503-S Switch Chassis (JD243B)

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		2
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		7
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

EL-MF877-00

Template Revision B

Tool Description	Tool Size (if applicable)
Screw driver	2#

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 2, and then remove mounting angle 2.
2. Unscrew the screws on cabling rack 3, and then remove cabling rack 3 from mounting angle 2.
3. Unscrew the screws on filler panel 4, and then remove filler panel 4.
4. Unscrew the screws on power supply module 5, and then remove power supply module 5.
5. Unscrew the screws on card 6, and then remove card 6.
6. Unscrew the screws on card 7, and then remove card 7.
7. Unscrew the screws on card 8, and then remove card 8.
8. Unscrew the screws on filler panel 9, and then remove filler panel 9.
9. Unscrew the screws on fan module frame 10, and then remove fan module frame 10.
10. Remove the film 11 from chassis 1.
11. Remove the film 12 from chassis 1.
12. Remove the shielding finger 13 from chassis 1.
13. Unscrew the screws on rear cover plate 14, and then remove rear cover plate 14.
14. Unscrew the screws on pull handle 14-2, and then remove pull handle 14-2 from cover 14-1.
15. Unscrew the screws on part 14-3, and then remove part 14-3 from cover 14-1.
16. Unscrew the screws on cover plate 14-4, and then remove cover 14-4.
17. Remove all of the inner cables.
18. Unscrew the screws on PCB 15, and then remove PCB 15.
19. Remove all of the labels.
20. Remove shielding finger 4-2 from filler panel 4-1.
21. Unscrew the screws on PCB 6-2, and then remove PCB 6-2.
22. Remove insulation film 6-3 from front panel 6-1.
23. Remove conductive foam 6-4 from front panel 6-1.
24. Remove shielding finger 6-5 from front panel 6-1.
25. Unscrew the screws on PCB 7-2, and then remove PCB 7-2 from panel 7-1.
26. Remove light pipe 7-3 from PCB 7-2.
27. Remove film 7-5 from front panel 7-1.
28. Remove shielding finger 7-4 from front panel 7-1.
29. Unscrew the screws on PCB 8-2, and then remove PCB 8-2.
30. Unscrew the screws on PCB 8-3, and then remove PCB 8-3.
31. Remove memory card 8-5, part 8-5, RF card 8-6, CF card 8-7.
32. Remove film 8-8 from panel 8-1.
33. Remove thermal conductive pad 8-10 from panel 8-1.
34. Remove all of the labels.
35. Remove shielding finger 8-9 from panel 8-1.
36. Remove film 9-2 from filler panel 9-1.
37. Remove shielding finger 9-3 from filler panel 9-1.
38. Unscrew the screws on the three fans 10-2, and then remove fans 10-2.
39. Unscrew the screws on PCB 10-3, and then remove PCB 10-3.
40. Remove all of the inner cables.
41. Unscrew the screws on handle 10-4, and then remove handle 10-4.
42. Remove film 10-5 from fan frame 10-1.
43. Remove shielding finger 10-6 from fan frame 10-1.

44. Remove connector 10-7.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

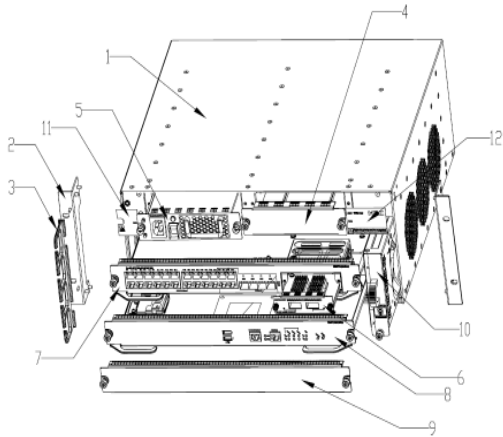


Figure 1 Front of H3C WX6103

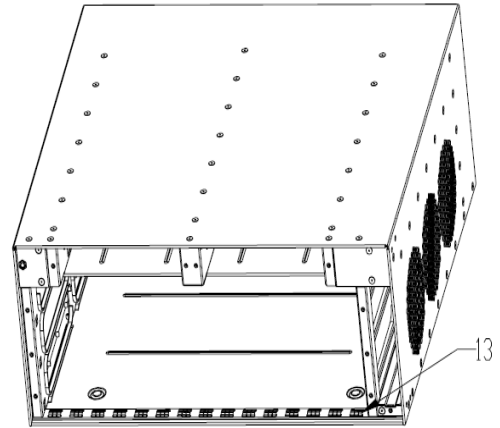


Figure 2 Front of H3C WX6103

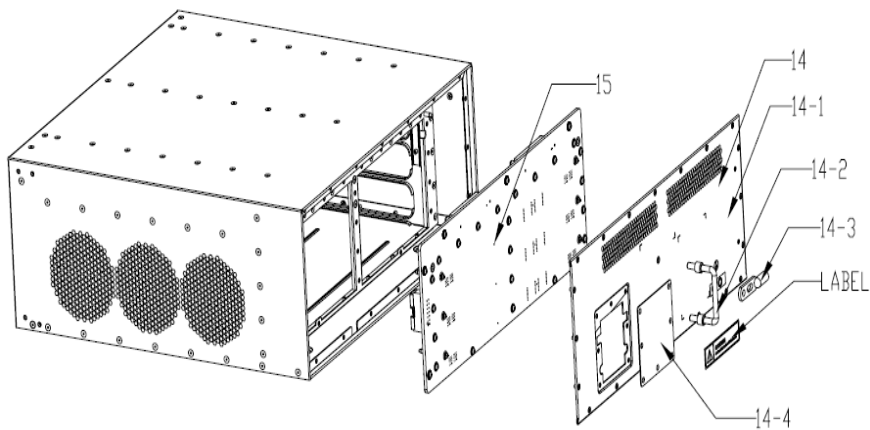


Figure 3 Rear of H3C WX6103

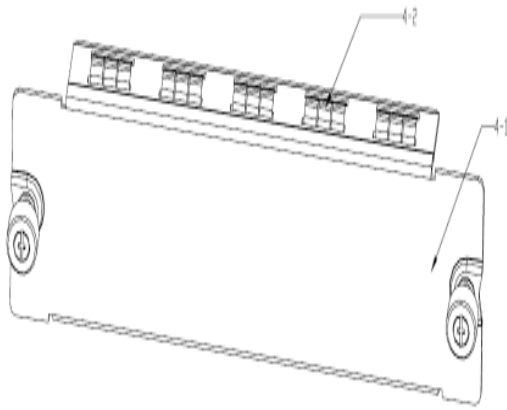


Figure 4 Treatments to filler panel 4

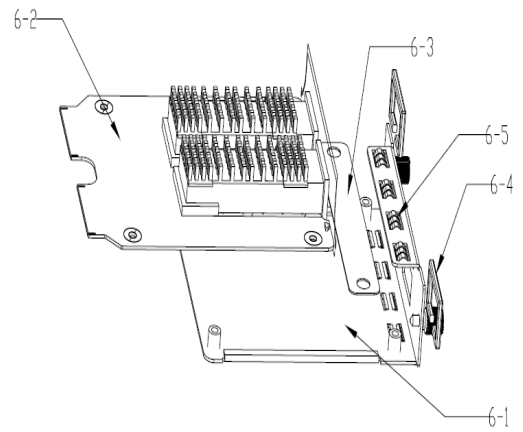


Figure 5 Treatments to card 6

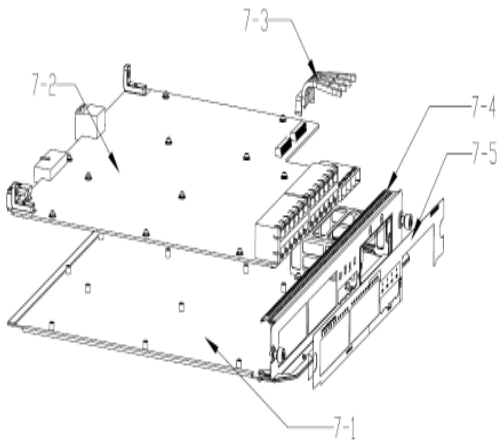


Figure 6 Treatments to card 7

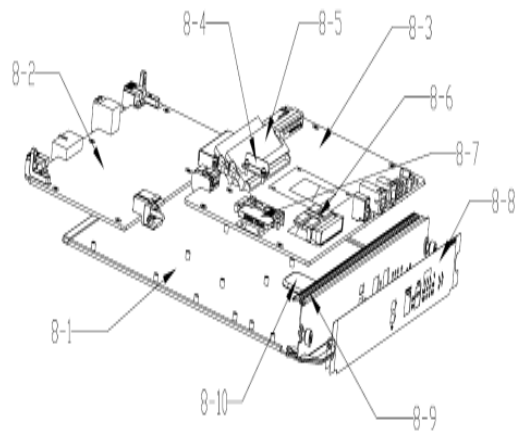


Figure 7 Treatments to card 8

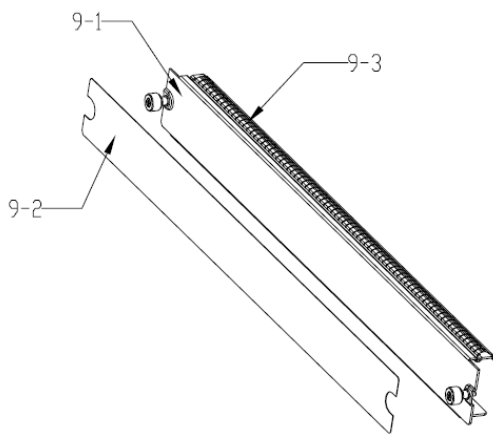


Figure 8 Treatments to filler panel 9

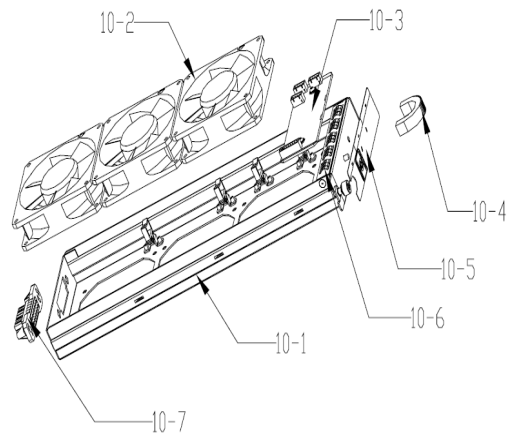


Figure 9 Treatments to fan module frame 10